

AMENDMENTS TO THE ABSTRACT

Please cancel the current Abstract and replace it with the following new Abstract:

A design support apparatus supports wiring design for bond wires that connect a semiconductor chip and an interposer. The design support apparatus includes a creating unit that creates simulated design data simulating occurrence of fluctuation in an arrangement position of a semiconductor chip on an interposer and occurrence of fluctuation in bond wire connection terminal positions of the interposer, and an analyzing unit that analyzes, based on the simulated design data, deficiencies in manufacturing of semiconductor devices due to the fluctuation in the arrangement position of the semiconductor chip on the interposer and the fluctuation in the bond wire connection terminal positions of the interposer.